

The SN5405 is obsolete and no longer is supplied.

SN54LS05, SN54S05 SN7405, SN74LS05, SN74S05 HEX INVERTERS WITH OPEN-COLLECTOR OUTPUTS

SDLS030A – DECEMBER 1983 – REVISED NOVEMBER 2003

- Package Options Include Plastic Small-Outline (D, NS), Shrink Small-Outline (DB), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) DIPs

- Dependable Texas Instrument Quality and Reliability

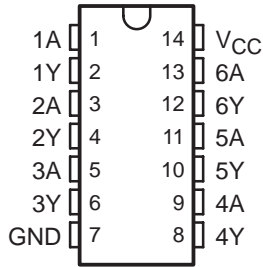
SN5405, SN54LS05, SN54S05 . . . J PACKAGE

SN7405 . . . N PACKAGE

SN74LS05 . . . D, DB, N, OR NS PACKAGE

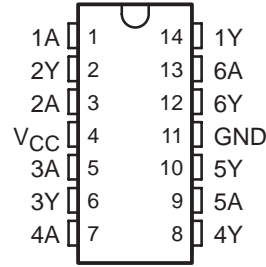
SN74S05 . . . D, N, OR NS PACKAGE

(TOP VIEW)



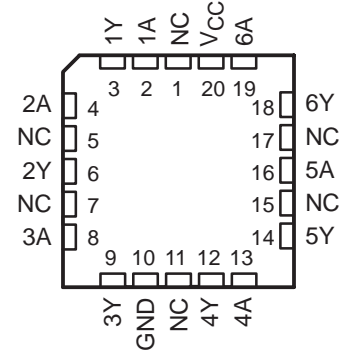
SN54LS05, SN54S05 . . . W PACKAGE

(TOP VIEW)



SN54LS05, SN54S05 . . . FK PACKAGE

(TOP VIEW)



NC – No internal connection

description/ordering information

These devices contain six independent inverters. To perform correctly, the open-collector outputs require pullup resistors. These devices may be connected to other open-collector outputs to implement active-low wired-OR or active-high wire-AND functions. Open-collector devices often are used to generate high V_{OH} levels.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	PDIP – N	Tube	SN7405N	SN7405N	
			SN74LS05N	SN74LS05N	
			SN74S05N	SN74S05N	
	SOIC – D	Tube	SN74LS05D	LS05	
			Tape and reel		SN74LS05DR
			Tube	SN74S05D	S05
				Tape and reel	
SOP – NS	Tape and reel	SN74LS05NSR	74LS05		
		SN74S05NSR	74S05		
–55°C to 125°C	CDIP – J	Tube	SNJ54LS05J	SNJ54LS05J	
			SNJ54S05J	SNJ54S05J	
	CDIP – W	Tube	SNJ54LS05W	SNJ54LS05W	
			SNJ54S05W	SNJ54S05W	
	LCCC – FK	Tube	SNJ54LS05FK	SNJ54LS05FK	
SNJ54S05FK			SNJ54S05FK		

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54LS05, SN54S05
SN7405, SN74LS05, SN74S05
HEX INVERTERS WITH OPEN-COLLECTOR OUTPUTS

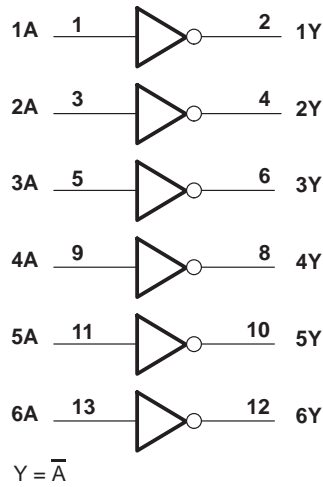
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FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, and NS packages.

**SN54LS05, SN54S05
SN7405, SN74LS05, SN74S05
HEX INVERTERS WITH OPEN-COLLECTOR OUTPUTS**

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recommended operating conditions

	SN5405			SN7405			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.8			0.8	V
V _{OH} High-level output voltage			5.5			5.5	V
I _{OL} Low-level output current			16			16	mA
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†		SN5405			SN7405			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN,	I _I = -12 mA			-1.5			-1.5	V
I _{OH}	V _{CC} = MIN,	V _{OH} = 5.5 V					0.25		mA
		V _{IH} = 0.8 V							
		V _{IL} = 0.7 V			0.25				
V _{OL}	V _{CC} = MIN,	V _{IH} = 2 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I _I	V _{CC} = MAX,	V _I = 5.5 V			1			1	mA
I _{IH}	V _{CC} = MAX,	V _I = 2.4 V			40			40	µA
I _{IL}	V _{CC} = MAX,	V _I = 0.4 V			-1.6			-1.6	mA
I _{CCH}	V _{CC} = MAX,	V _I = 0 V		6	12		6	12	mA
I _{CCL}	V _{CC} = MAX,	V _I = 4.5 V		18	33		18	33	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t _{PLH}	A	Y	R _L = 4 kΩ	C _L = 15 pF		40	55	ns
t _{PHL}			R _L = 400 Ω			8	15	



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SN54LS05, SN54S05
SN7405, SN74LS05, SN74S05
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recommended operating conditions

		SN54LS05			SN74LS05			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage				0.7			V
V _{OH}	High-level output voltage				5.5			V
I _{OL}	Low-level output current				4			mA
T _A	Operating free-air temperature	-55			125			°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS05			SN74LS05			UNIT	
		MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V _{IK}	V _{CC} = MIN, I _I = -18 mA				-1.5			V	
I _{OH}	V _{CC} = MIN, V _{IL} = MAX, V _{OH} = 5.5 V				0.1			mA	
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V	I _{OL} = 4 mA		0.25		0.4		V	
		I _{OL} = 8 mA				0.35			
I _I	V _{CC} = MAX, V _I = 7 V				0.1			mA	
I _{IH}	V _{CC} = MAX, V _I = 2.7 V				20			µA	
I _{IL}	V _{CC} = MAX, V _I = 0.4 V				-0.4			mA	
I _{CCH}	V _{CC} = MAX, V _I = 0 V				1.2		2.4		mA
I _{CCL}	V _{CC} = MAX, V _I = 4.5 V				3.6		6.6		mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	A	Y	R _L = 2 kΩ, C _L = 15 pF	17		32	ns
t _{PHL}				15		28	



**SN54LS05, SN54S05
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recommended operating conditions

	SN54S05			SN74S05			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.8			0.8	V
V _{OH} High-level output voltage			5.5			5.5	V
I _{OL} Low-level output current			20			20	mA
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†		SN54S05			SN74S05			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN,	I _I = -18 mA			-1.2			-1.2	V
I _{OH}	V _{CC} = MIN,	V _{OH} = 5.5 V					0.25		mA
		V _{IL} = 0.8 V							
		V _{IL} = 0.7 V			0.25				
V _{OL}	V _{CC} = MIN,	V _{IH} = 2 V, I _{OL} = 20 mA			0.5			0.5	V
I _I	V _{CC} = MAX,	V _I = 5.5 V			1			1	mA
I _{IH}	V _{CC} = MAX,	V _I = 2.7 V			50			50	µA
I _{IL}	V _{CC} = MAX,	V _I = 0.5 V			-2			-2	mA
I _{CCH}	V _{CC} = MAX,	V _I = 0 V		9	19.8		9	19.8	mA
I _{CCL}	V _{CC} = MAX,	V _I = 4.5 V		30	54		30	54	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

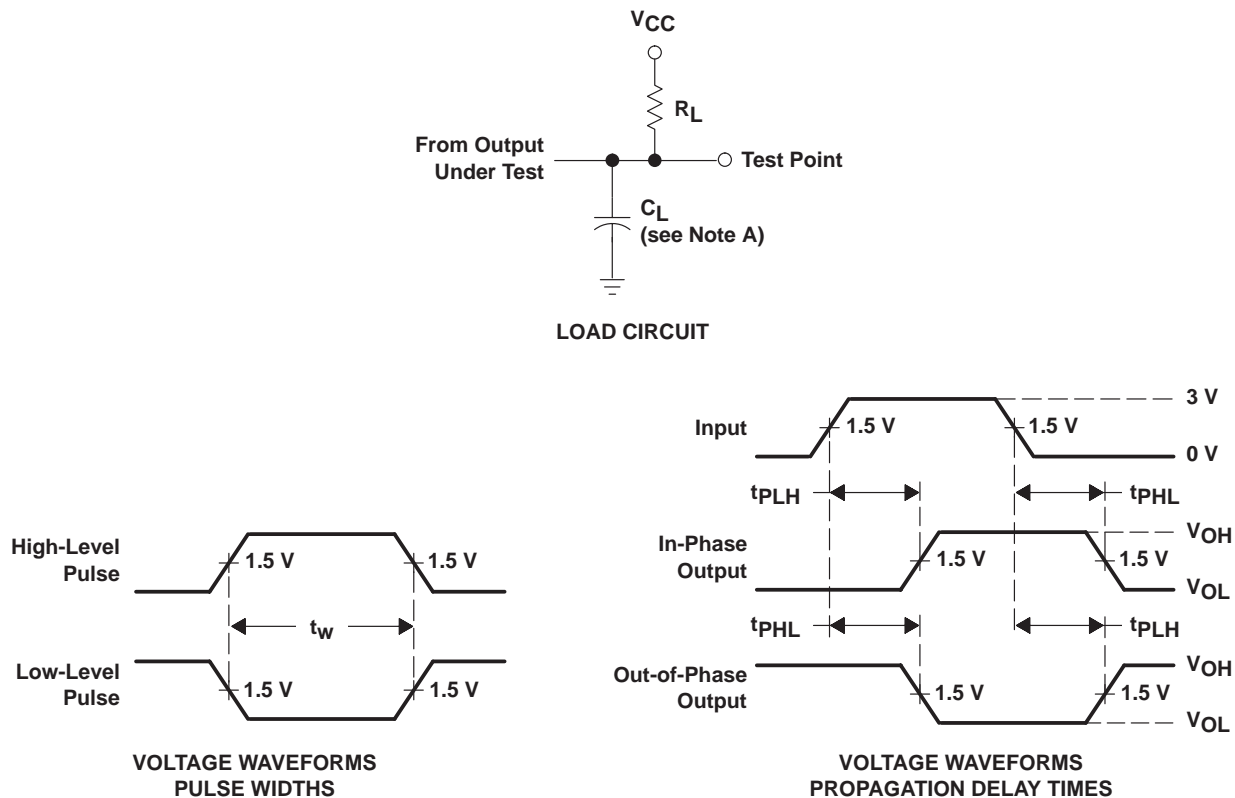
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t _{PLH}	A	Y	R _L = 280 Ω	C _L = 15 pF	2	5	7.5	ns
t _{PHL}					2	4.5	7	
t _{PLH}				C _L = 50 pF	7.5	ns		
t _{PHL}					7			



**PARAMETER MEASUREMENT INFORMATION
SERIES 54/74 AND 54S/74S DEVICES**



- NOTES: A. C_L includes probe and jig capacitance.
 B. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, and:
 For Series 54/74, $t_r \leq 7$ ns, $t_f \leq 7$ ns.
 For Series 54S/74S, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.

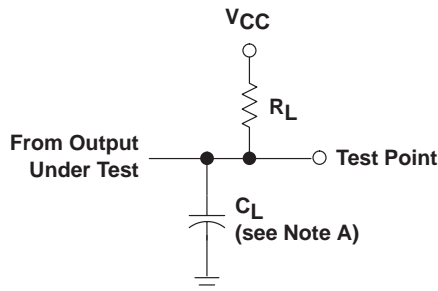
Figure 1. Load Circuit and Voltage Waveforms

**SN54LS05, SN54S05
SN7405, SN74LS05, SN74S05
HEX INVERTERS WITH OPEN-COLLECTOR OUTPUTS**

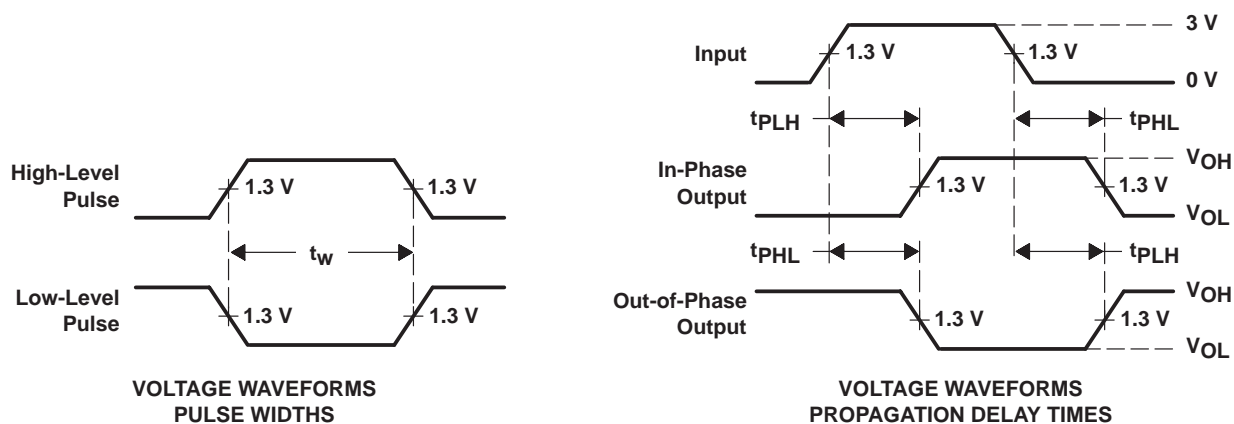
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**PARAMETER MEASUREMENT INFORMATION
SERIES 54LS/74LS DEVICES**



LOAD CIRCUIT



- NOTES: A. C_L includes probe and jig capacitance.
 B. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r \leq 1.5$ ns, $t_f \leq 2.6$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07004BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07004BCA	Samples
M38510/07004BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07004BCA	Samples
SN54LS05J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS05J	Samples
SN54S05J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S05J	Samples
SN7405D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN7405DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70		
SN7405N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7405N	Samples
SN7405N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN7405NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN7405N	Samples
SN74LS05D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS05	Samples
SN74LS05DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI	0 to 70		
SN74LS05DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS05	Samples
SN74LS05DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS05	Samples
SN74LS05DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS05	Samples
SN74LS05DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS05	Samples
SN74LS05N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS05N	Samples
SN74LS05N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS05NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS05N	Samples
SN74LS05NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS05	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74S05D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S05	Samples
SN74S05N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S05N	Samples
SN74S05N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74S05NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S05N	Samples
SN74S05NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74S05	Samples
SNJ54LS05FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS05FK	Samples
SNJ54LS05J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS05J	Samples
SNJ54LS05W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS05W	Samples
SNJ54S05FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54S05FK	Samples
SNJ54S05J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S05J	Samples
SNJ54S05W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S05W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS05, SN54S05, SN7405, SN74LS05, SN74S05 :

- Catalog: [SN74LS05](#), [SN74S05](#)
- Military: [SN5405](#), [SN54LS05](#), [SN54S05](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS05DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LS05DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS05NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74S05NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS05DBR	SSOP	DB	14	2000	367.0	367.0	38.0
SN74LS05DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS05NSR	SO	NS	14	2000	367.0	367.0	38.0
SN74S05NSR	SO	NS	14	2000	367.0	367.0	38.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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